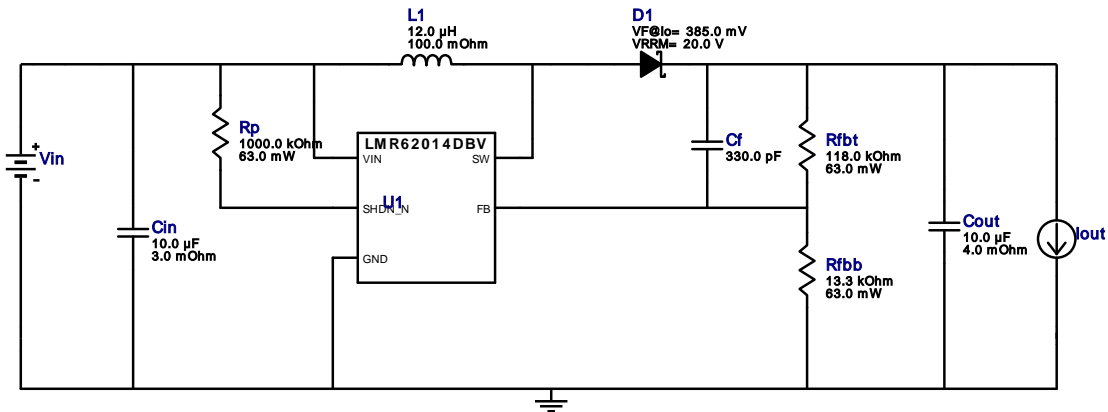


VinMin = 5.0V  
VinMax = 5.0V  
Vout = 12.0V  
Iout = 0.3A

Device = LMR62014XMF/NOPB  
Topology = Boost  
Created = 2022-04-01 04:38:23.325  
BOM Cost = \$0.62  
BOM Count = 9  
Total Pd = 0.51W

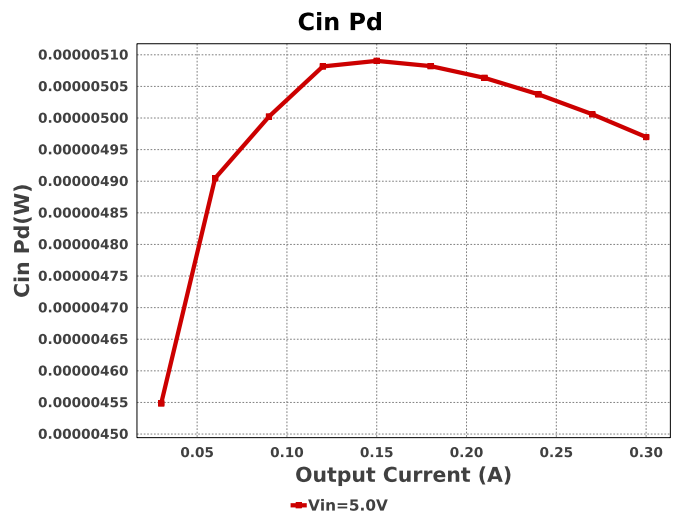
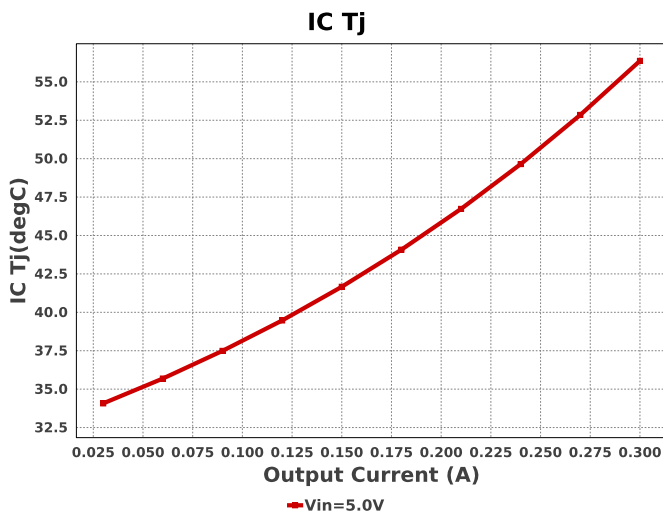
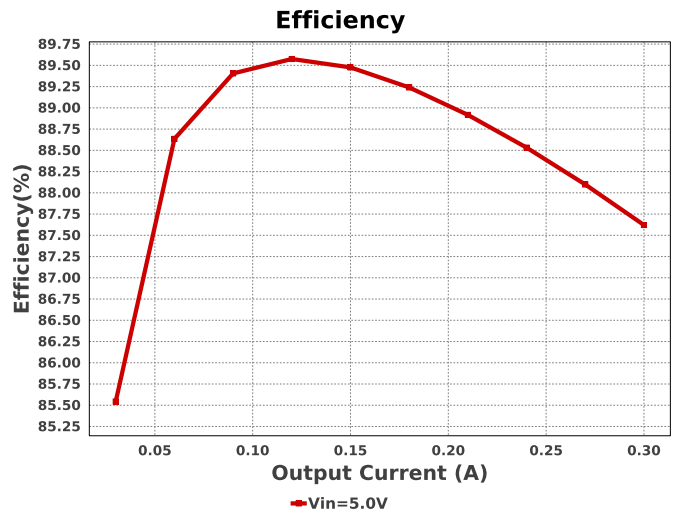
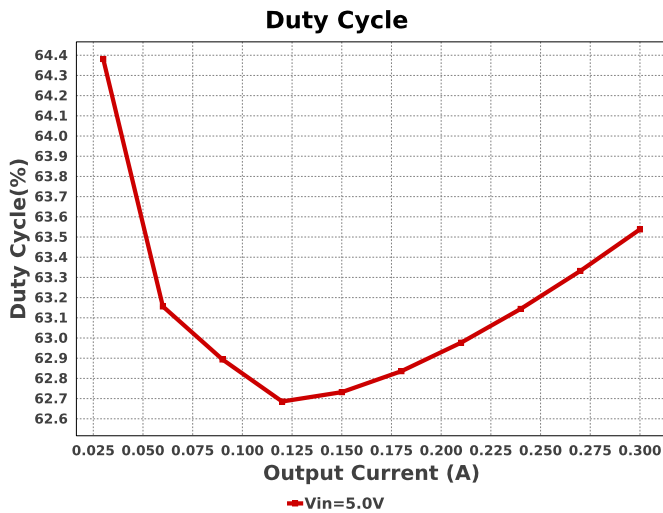
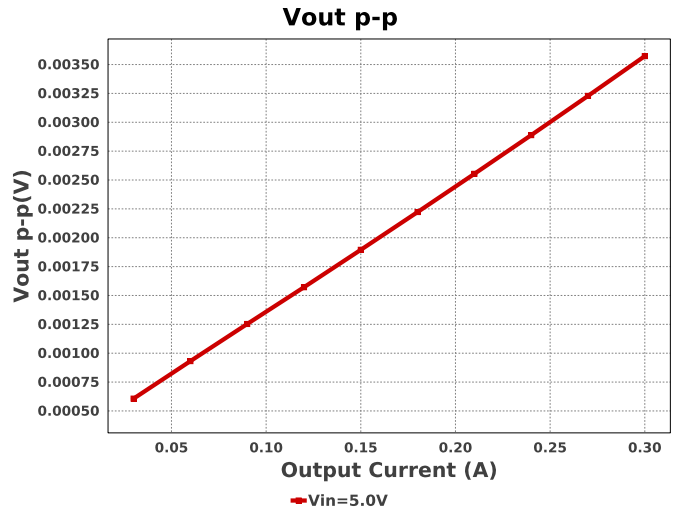
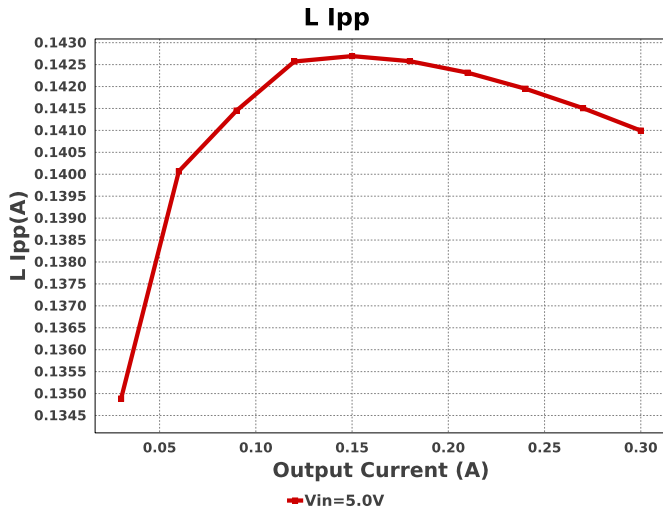
## WEBENCH® Design Report

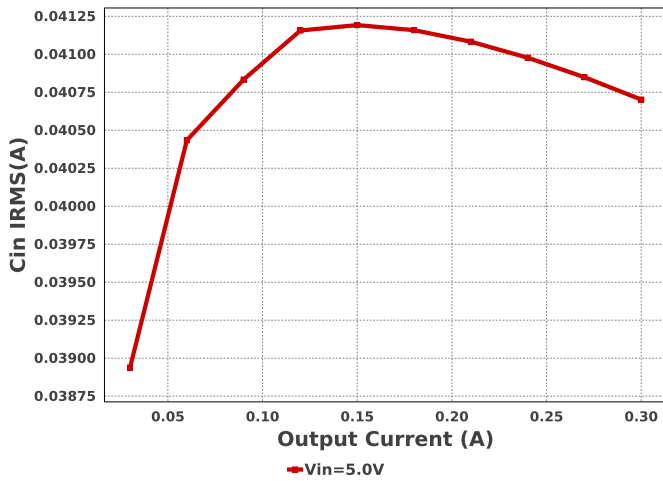
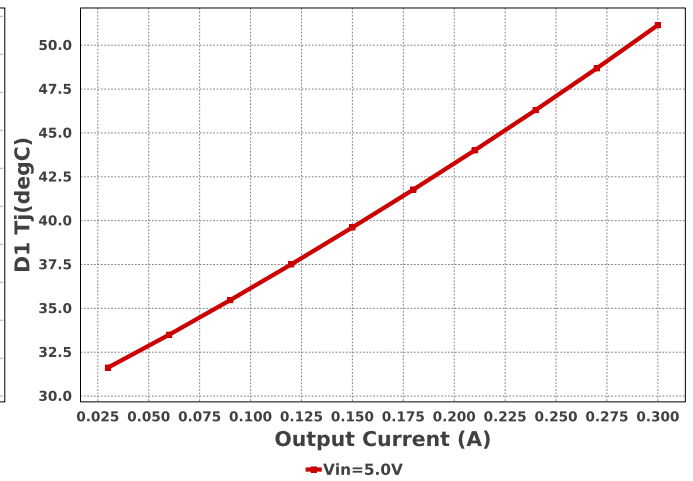
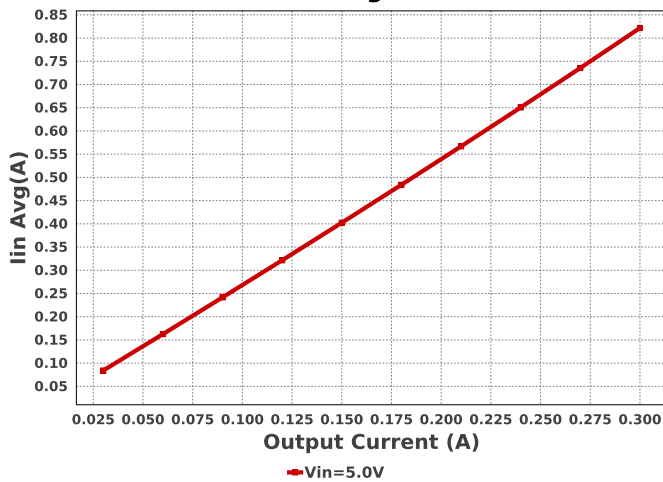
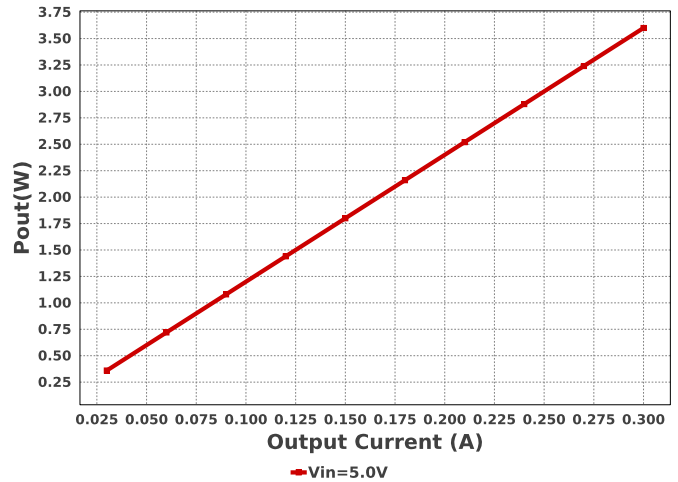
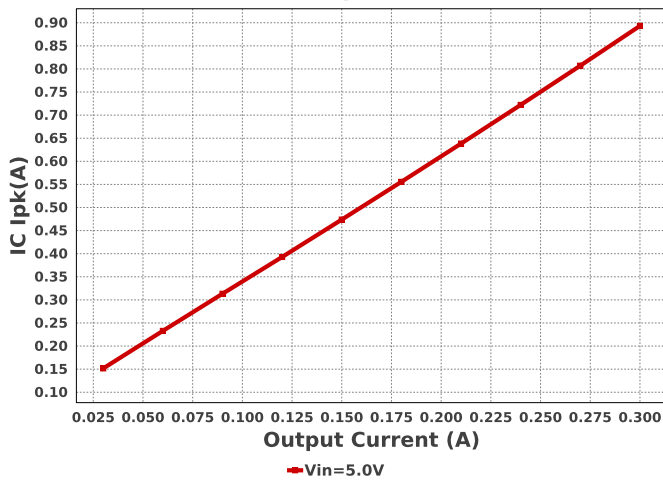
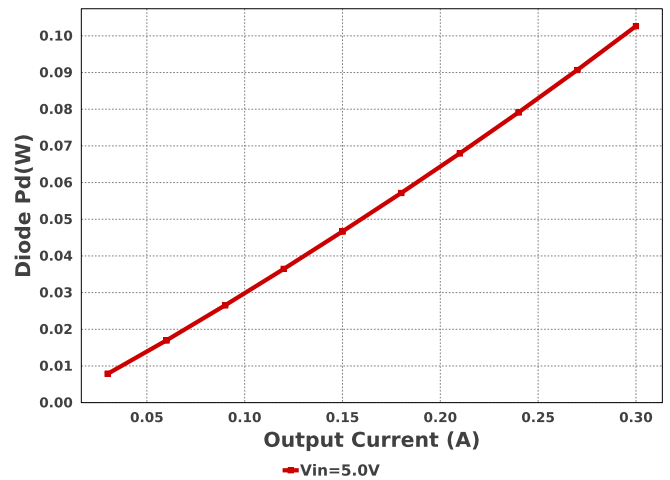
Design : 9 LMR62014XMF/NOPB  
LMR62014XMF/NOPB 5V-5V to 12.00V @ 0.3A

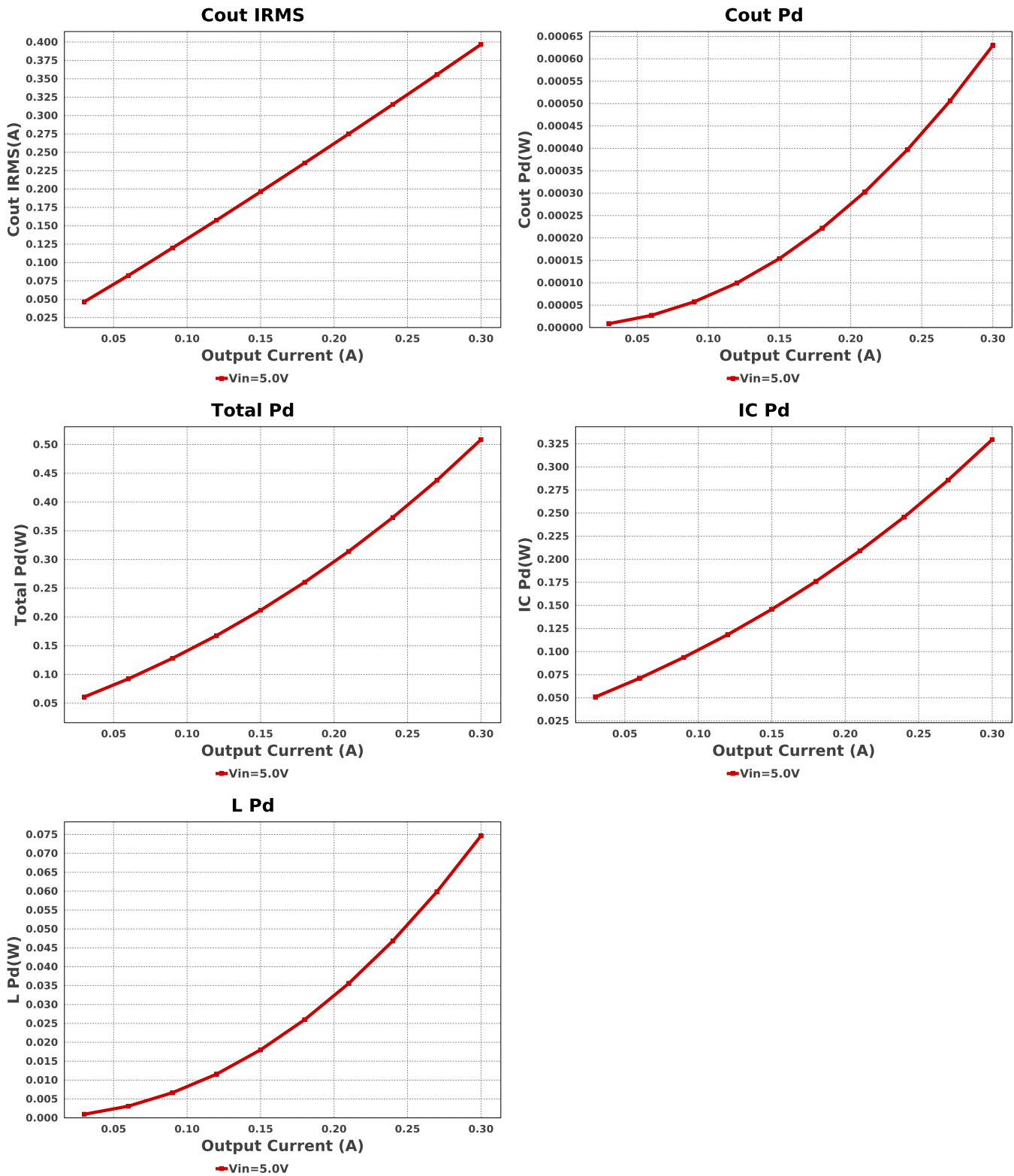


### Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cf	Samsung Electro-Mechanics	CL21C331JBANNNC Series= C0G/NP0	Cap= 330.0 pF VDC= 50.0 V IRMS= 0.0 A	1	\$0.01	0805 7 mm <sup>2</sup>
Cin	Kemet	C0805C106K8PACTU Series= X5R	Cap= 10.0 uF ESR= 3.0 mOhm VDC= 10.0 V IRMS= 11.43 A	1	\$0.03	0805 7 mm <sup>2</sup>
Cout	MuRata	GRM21BR61E106MA73L Series= X5R	Cap= 10.0 uF ESR= 4.0 mOhm VDC= 25.0 V IRMS= 2.8 A	1	\$0.05	0805 7 mm <sup>2</sup>
D1	ON Semiconductor	MBR0520LT1G	VF@Io= 385.0 mV VRRM= 20.0 V	1	\$0.05	SOD-123 13 mm <sup>2</sup>
L1	NIC Components	NPI54C120MTRF	L= 12.0 uH 100.0 mOhm	1	\$0.12	IND_NPI54C 61 mm <sup>2</sup>
Rfbb	Vishay-Dale	CRCW040213K3FKED Series= CRCW..e3	Res= 13.3 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
Rfbbt	Vishay-Dale	CRCW0402118KFKED Series= CRCW..e3	Res= 118.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
Rp	Vishay-Dale	CRCW04021M00FKED Series= CRCW..e3	Res= 1000.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
U1	Texas Instruments	LMR62014XMF/NOPB	Switcher	1	\$0.33	DBV0005A 15 mm <sup>2</sup>



**Cin IRMS****D1 Tj****Iin Avg****Pout****IC Ipk****Diode Pd**



## Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	40.702 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	4.97 $\mu$ W	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	396.782 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	629.74 $\mu$ W	Capacitor	Output capacitor power dissipation
5.	D1 Tj	51.146 degC	Diode	D1 junction temperature
6.	Diode Pd	102.65 mW	Diode	Diode power dissipation
7.	IC Ipk	893.27 mA	IC	Peak switch current in IC
8.	IC Pd	329.56 mW	IC	IC power dissipation
9.	IC Tj	56.365 degC	IC	IC junction temperature
10.	Iin Avg	821.72 mA	IC	Average input current
11.	L Ipp	141.0 mA	Inductor	Peak-to-peak inductor ripple current

#	Name	Value	Category	Description
12.	L Pd	74.647 mW	Inductor	Inductor power dissipation
13.	Cin Pd	4.97 $\mu$ W	Power	Input capacitor power dissipation
14.	Cout Pd	629.74 $\mu$ W	Power	Output capacitor power dissipation
15.	Diode Pd	102.65 mW	Power	Diode power dissipation
16.	IC Pd	329.56 mW	Power	IC power dissipation
17.	L Pd	74.647 mW	Power	Inductor power dissipation
18.	Total Pd	508.604 mW	Power	Total Power Dissipation
19.	BOM Count	9	System	Total Design BOM count
			Information	
20.	Duty Cycle	63.538 %	System	Duty cycle
			Information	
21.	Efficiency	87.621 %	System	Steady state efficiency
			Information	
22.	FootPrint	118.0 mm <sup>2</sup>	System	Total Foot Print Area of BOM components
			Information	
23.	Frequency	1.6 MHz	System	Switching frequency
			Information	
24.	Iout	300.0 mA	System	Iout operating point
			Information	
25.	Mode	CCM	System	Conduction Mode
			Information	
26.	Pout	3.6 W	System	Total output power
			Information	
27.	Total BOM	\$0.62	System	Total BOM Cost
			Information	
28.	Vin	5.0 V	System	Vin operating point
			Information	
29.	Vout Actual	12.143 V	System	Vout Actual calculated based on selected voltage divider resistors
			Information	
30.	Vout Tolerance	3.885 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
			Information	
31.	Vout p-p	3.573 mV	System	Peak-to-peak output ripple voltage
			Information	

## Design Inputs

Name	Value	Description
Iout	300.0 m	Maximum Output Current
VinMax	5.0	Maximum input voltage
VinMin	5.0	Minimum input voltage
Vout	12.0	Output Voltage
base_pn	LMR62014X	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

## WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of  $C_{in}$  and  $C_{out}$ , and the inductance and DC resistance of  $L1$  before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 5.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to  $V_{in}$  and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from  $V_{out}$  and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between  $V_{in}$  and GND, a load is connected between  $V_{out}$  and GND and a current meter is connected in series between  $V_{out}$  and the load. The load must be able to handle at least rated output power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



### Design Assistance

1. Master key : E4B9CFD1C57BC38D[v1]
2. **LMR62014X** Product Folder : <http://www.ti.com/product/LMR62014> : contains the data sheet and other resources.

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